607 Series

Lead-free > 10x32mm Fuse

Description

The 607 series fuses are specifically designed and tested to cater to the circuit protection needs of compact applications, which is 500Vdc/Vac rated with remarkable interrupting rating.

Features & Benefits

- RoHS compliant and Lead-free
- High Interrupt Rating
- Rated voltage 500 Vdc/Vac
- Small size
- High current
- High voltage
- High breaking capacity

Applications

- Data Center Power Supplies
- Uninterruptible Power Supply (UPS)
- Power conversion equipment like inverters and rectifiers

Web Resources

Download ECAD models, order samples, and find technical recources at www.littelfuse.com

Electrical Characteristics

% of Ampere Rating	Ampere Rating	Opening Time at 25°C
100%	40 A to 63 A	4hrs, Min.
200%	40 A to 63 A	120 seconds, Max.

Agency Approvals

Agency	Agency File Number	Ampere Range
c UL us	E71611	40 A to 63 A
	J 50514752	40 A to 63 A

Electrical Specifications

Ampere Rating (A)	Amp Code	Max Voltage Rating (V)	Interrupting Rating (AC/DC)	Nominal Code Resistance (Ohms)	Nominal Melting I²t (A²sec)	Agency Approvals		
						c UL us		CE
40	040.	500VDC 500VAC 305VAC	10KA@500VDC 10KA@500VAC 47KA@305VAC	0.00187	2570	x	x	x
50	050.			0.00145	4230	x	x	x
63	063.	500VDC 500VAC 305VAC	10KA@500VDC 5KA@500VAC 47KA@305VAC	0.00102	7060	x	x	x

Note

Unless otherwise stated, all specifications are referenced at room ambient temperature.
Interrupting Rating may differ based on Agency Approval. See Agency Approval certificate for more details.

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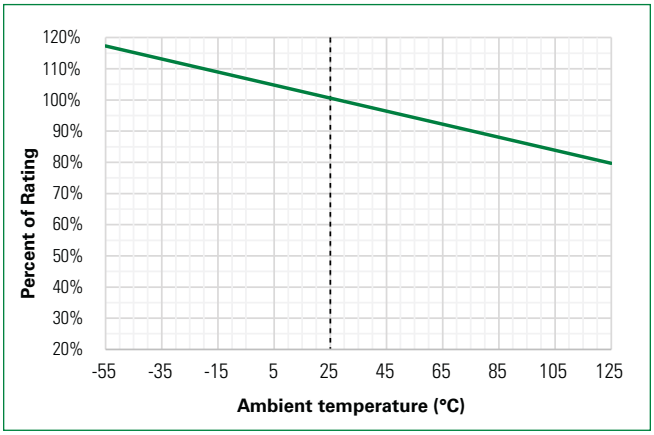
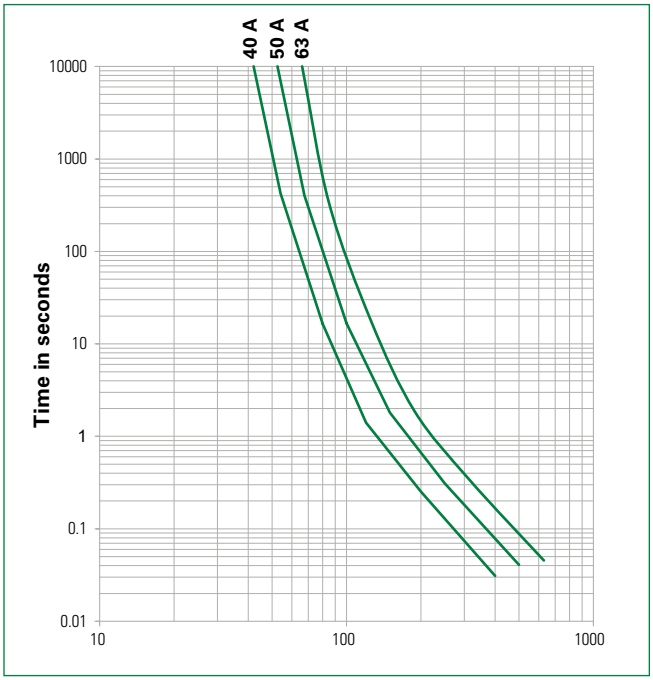
Temperature Re-rating Curve



Note:
Rerating depicted in this curve is in addition to the standard derating of 25% for continuous operation.

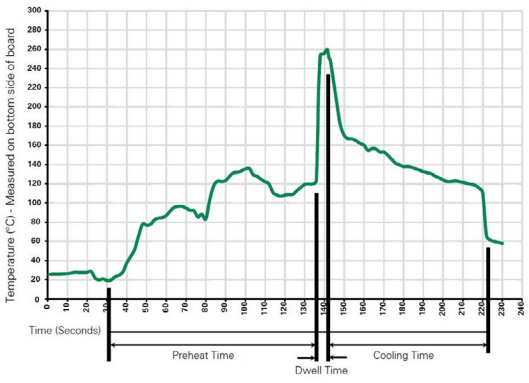
Average Time Current Curves



Product Characteristics

Materials	**Body:** Glass fiber **Cap:** Ni plated copper alloy **Terminal:** Tin plated copper alloy
Mechanical Shock	MIL-STD-202, Method 213, Test Condition I (100 G's peak for 6 milliseconds)
Solderability	Reference MIL-STD-202 method 208
Product Marking	Cap 1: Brand logo, current and voltage ratings Cap 2: Agency approval marks
Resistance to Solder Heat	MIL-Std 202 Method 210 Test Condition B (10sec at 260 °C)
Operating Temperature	-55 °C to +125 °C
Thermal Shock	MIL-STD-202G, Method 107G, Test condition B
Vibration	MIL-STD-202G, Method 201A
Moisture Resistance	MIL-STD-202G, Method 103B, Test condition A
Salt Spray	MIL-STD-202G, Method 101E, Test condition B

Soldering Parameters–Wave Soldering



Wave Parameter	Lead-Free Recommendation
Preheat: (Depends on Flex Activation Temperature)	(Typical Industry Recommendation)
Temperature Minimum	100 °C
Temperature Maximum	150 °C
Preheat Time	60–180 seconds
Solder Pot Temperature	260 °C Maximum
Solder Dwell Time	2–5 seconds

Recommended Hand-Solder Parameters:
Solder Iron Temperature: 350 °C +/- 5 °C
Heating Time: 5 seconds max.
Note: These devices are not recommended for IR or Convection Reflow process.

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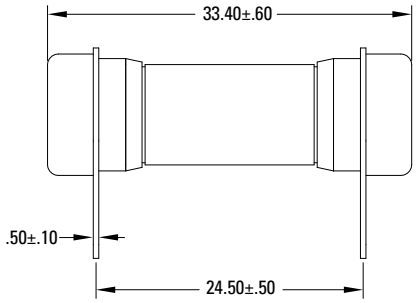
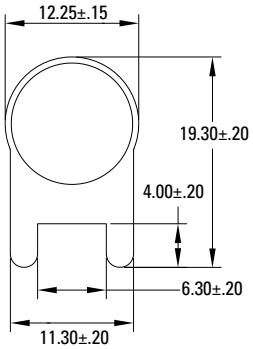
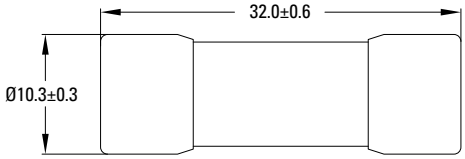
Dimensions

UXTH

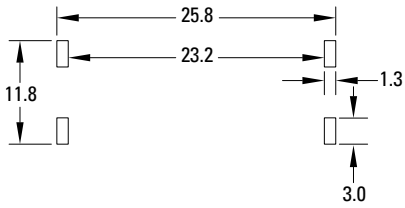




UX



Recommended PCB Layout



All dimensions in mm

Part Numbering System

0607 xxxx U X TH500 P

- **Series**
- **Amp Code** Refer to Amp Code column of Electrical Characteristics Table
- **Quantity Code** U=500
- **Packaging Code** X= Filler
- **Option Code** TH: Through hole type terminal; Blank: Cartridge Type Fuse
- **P: Lead-Free**

Packaging

Packaging Option	Packaging Specification	Quantity	Quantity & Packaging Code	Reel Size
		607 Series		
Tray	NA	500	NA	NA

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